



Click here for the 3D model.

D 6.3mm +/-0.5mm   L 7.7mm +/-0.3mm   W 0.65mm +/-0.1mm   F 0.3mm MAX   A 6.6mm +/-0.2mm   B 6.6mm +/-0.2mm   C 7.8mm MAX   E 2.6mm +/-0.2mm   G 0.35mm +0.15/-0.2mm	Dimensions	
W 0.65mm +/-0.1mm   F 0.3mm MAX   A 6.6mm +/-0.2mm   B 6.6mm +/-0.2mm   C 7.8mm MAX   E 2.6mm +/-0.2mm   G 0.35mm +0.15/-0.2mm	D	6.3mm +/-0.5mm
F 0.3mm MAX   A 6.6mm +/-0.2mm   B 6.6mm +/-0.2mm   C 7.8mm MAX   E 2.6mm +/-0.2mm   G 0.35mm +0.15/-0.2mm	L	7.7mm +/-0.3mm
A 6.6mm +/-0.2mm   B 6.6mm +/-0.2mm   C 7.8mm MAX   E 2.6mm +/-0.2mm   G 0.35mm +0.15/-0.2mm	W	0.65mm +/-0.1mm
B 6.6mm +/-0.2mm   C 7.8mm MAX   E 2.6mm +/-0.2mm   G 0.35mm +0.15/-0.2mm	F	0.3mm MAX
C   7.8mm MAX     E   2.6mm +/-0.2mm     G   0.35mm +0.15/-0.2mm	А	6.6mm +/-0.2mm
E 2.6mm +/-0.2mm G 0.35mm +0.15/-0.2mm	В	6.6mm +/-0.2mm
G 0.35mm +0.15/-0.2mm	С	7.8mm MAX
	E	2.6mm +/-0.2mm
	G	0.35mm +0.15/-0.2mm
P 1.8mm +/-0.2mm	Р	1.8mm +/-0.2mm

Packaging Specifications		
Packaging	T&R, 380mm	
Packaging Quantity	1000	

General Information		
Series	EEV	
Dielectric	Aluminum Electrolytic	
Style	SMD Can	
Description	Surface Mount, Aluminum Electrolytic	
RoHS	Yes	
Lead	V-Chip	
Qualifications	AEC-Q200	
AEC-Q200	Yes	

Specifications	
Capacitance	220 uF
Capacitance Tolerance	20%
Voltage DC	16 VDC, 20 VDC (Surge)
Temperature Range	-55/+105°C
Rated Temperature	105°C
Life	2000 Hrs
<b>Dissipation Factor</b>	16% 120Hz 20C
Resistance	0.22 Ohms (100kHz 20C)
Ripple Current	196 mAmps (120Hz 105C), 224 mAmps (1kHz), 280 mAmps (100kHz)
Leakage Current	35.2 uA (2min 20°C)
Impedance Ratio at -25C	2
Impedance Ratio at -40C	3
High Temperature Solder	Yes

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